Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A method for providing a PCB (printed circuit board) with a shield can comprising a metal shell having a free rim, said method comprising the steps of:

providing the PCB with solder;

placing the shield can on the PCB with the rim towards the PCB;

heating the PCB and the shield can to a temperature above a melting temperature of the solder; and

cooling the PCB and the shield can, wherein the rim of the shield can is provided with an extra amount of solder before the shield can is placed on the PCB.

2. (Previously Presented) The method according to claim 1, wherein the rim of the shield can is provided with the extra amount of solder by dipping the rim partly into a bath of molten solder.

3. (Previously Presented) The method according to claim 1, wherein recesses are provided at the rim of the shield can before the extra amount of solder is applied thereto; and

wherein the extra amount of solder is applied to the recesses.

4. (Previously Presented) The method according to claim 1, wherein the rim of the shield can is provided with the extra amount of solder by a screen-printing process.

5. (Previously Presented) The method according to claim 1, wherein indentations are provided at the rim of the shield can before the extra amount of solder is applied thereto; and

wherein the extra amount of solder is applied to the indentations.

6. (Withdrawn) A shield can (1;11;21;31) for electro-magnetically shielding an electronic component mounted on a printed circuit board (PCB) provided with solder, said shield can (1;11;21;31) comprising a metal shell with a free rim (5;15;25;35), characterised in that the rim (5;15;25;35) of the shield can (1;11;21;31) is provided with an extra amount of solder (8;18).

7. (Withdrawn) A shield can according to claim 6, characterised in that the rim (15;25) of the shield can (11;21) is provided with a plurality of recesses (19;29), each recess (19;29) being provided with an extra amount of solder (18).

8. (Withdrawn) A shield can according to claim 7, characterised in that each recess (19;29) is V-shaped.

9. (Withdrawn) A shield can according to claim 6, characterised in that the rim (35) of the shield can (31) is provided with a plurality of indentations (39), each indentation (39) being provided with an extra amount of solder.

10. (Withdrawn) A shield can according to claim 9, characterised in that each indentation (39) is V-shaped.

11. (Withdrawn) A shield can according to any one of claims 6-10, characterised in that the shield can (1;11;21;31) is box-shaped with a flat upper shell part (3;13) and four downwardly extending side pieces (4;14;24;34) with the free rim (5;15;25;35).

12. (Withdrawn) A shield can according to claim 11, characterised in that the side pieces (14;24;34) are interconnected at adjoining corners; and that each corner is provided with a leg (20) that protrudes downwards beyond the free rim (15;25;35).

13. (New) The method according to claim 1, wherein the extra amount of solder extends around substantially the entire perimeter of the rim of the shield can.